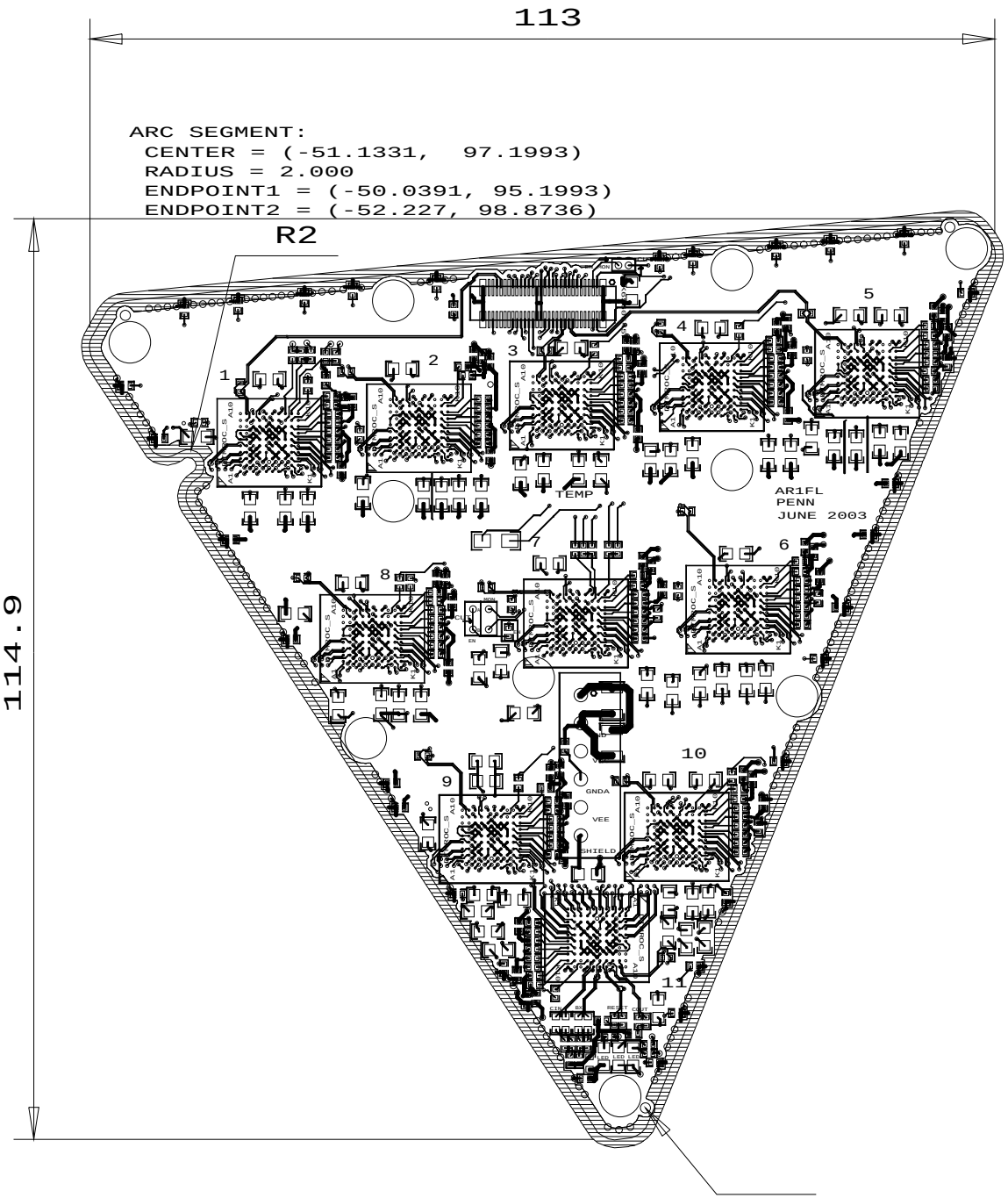

BOARD NAME: AR1FL

DATE: 16 JUNE 2003
UNIVERSITY OF PENNSYLVANIA
DEPT OF PHYSICS
CONTACTS: N. DRESSNANDT
(215) 573-3380

R. VAN BERG
(215) 898-5977

FILE: ar1fl_v23.brd

ASSEMBLY NOTES:

1. ALL DIMENSIONS IN MILS
2. THIS IS A 14 LAYER BOARD.
   ORDER OF LAYERS IS:
   - TOP
   - L2
   - L3VDD
   - L4GNDD
   - L5
   - L6
   - L7
   - L8VM
   - L9GNDA
   - L10VP
   - L11
   - L12
   - L13GNDA
   - BOTTOM

3. ALL VIAS ARE PLATED THROUGHT
   UNLESS OTHERWISE NOTED.

4. BOARD MATERIAL IS FR4
BOARD FINISH: SN-PB, HASL
6. BOARD THICKNESS: 0.062 inch APPROX.

7. LAYERS L6 AND L7 ARE EMPTY. THEY
ARE INTENDED TO INCREASE THE SEPARATION
DISTANCE BETWEEN LAYERS L5 AND L8VM.
PLEASE USE LOW-DIELECTRIC MATERIALS IN
THIS REGION TO MINIMIZE CAPACITIVE COUPLING.

8. LAYER L11 IS EMPTY.

9. TENT ALL VIAS NEAR BGA PADS WITH SOLDERMASK.

10. BGA PADS MUST NOT HAVE DRILL HOLES IN THEM.

11. THERE ARE 4 TYPES OF BLIND VIAS:
    - BLIND1: TOP, L2, L3, L4, L5
    - BLIND2: TOP, L2, L3, L4
    - BLIND3: BOTTOM, L13, L12
    - BLIND4: BOTTOM, L13, L12, L11, L10, L9, L8

12. 3.2 MM DIAMETER MOUNT HOLES ARE NON-PLATED THROUGH.

FIDUCIAL MARKS LOCATED AT:
(6, 17)
(-59, 116)
(44, 127)